

**METHODS OF FORMING METALLURGY STRUCTURES FOR
WIRE AND SOLDER BONDING AND RELATED STRUCTURES**

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ABSTRACT

Metallurgy structures for input/output pads of an electronic devices can be adapted to receive both solder and wire bonds. First and second metallurgy structures, for example, can be provided on respective first and second input/output pads of an electronic device such that the first and second common metallurgy structures have a shared structure adapted to receive both solder and wire bonds. A solder bond can thus be applied to the first metallurgy structure, and a wire bond can be applied to the second metallurgy structure.

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